Programming the Adapteva Epiphany 64-core Network-on-chip Coprocessor

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- Introduction
- 2 Architecture
 - Parallella Hardware Architecture
 - Software Environment
- Performance Experiments
 - On-chip Communication
 - Off-chip Communication
- 4 Heat Stencil
 - Implementation
 - Results
- Conclusions



Introduction

Adapteva Epiphany Coprocessor

- New scalable many-core architecture
- Energy efficient platform (50 GFLOPS/Watt)
- \$99 for a Parallella board

Contributions

- Explored features of the Epiphany
- Evaluated the performance
- Demonstrated how to write high performance applications on this platform

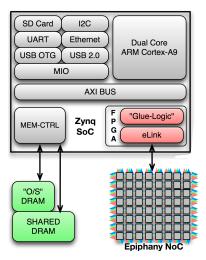


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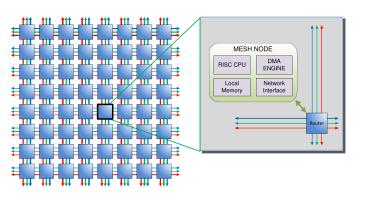


Conclusions

Parallella Board



Epiphany Coprocessor



Features

- Multi-core MIMD architecture
- No cache
- 32 KB of local SRAM in four banks of 8 KB
 - Shared address space
- 64 General purpose registers
- Epiphany Instruction set
- Superscalar CPU two floating point operations (Fused Multiply-Add) and one 64-bit memory load/store operation

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Software Environment

Programming Environment

- C/C++
- Epiphany SDK

Programming Considerations

- Memory Size
 - Relatively small 32 KB of local RAM per eCore (for storing both code and data)
 - Store code and data in different local memory banks
 - Distribute code between multiple cores
- Processor Capability
 - Currently no hardware support for integer multiply, floating point divide or double-precision floating point operations
 - Branching costs 3 cycles. Unroll inner loops to increase performance



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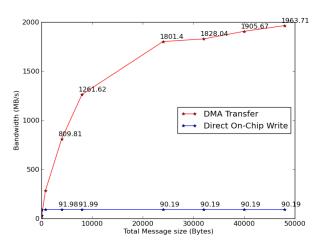


Experiment Platform

- ZedBoard evaluation module with Zynq SoC
- Daughter card with Epiphany-IV 64-core (E64G401)
- Dual core ARM Cortex-A9 host at 667 MHz
- Epiphany eCores at 600 MHz
- 512 MB of DDR3 RAM on the host
- 32 MB shared with eCores

Bandwidth

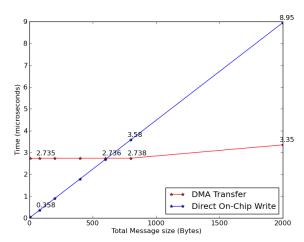
Experiment: To evaluate cost of sending messages from one eCore to another





Latency

Latency for small message transfers





Latency

Experiment: To evaluate the effect of Node distance on Transfer Latency

Node 1	Node 2	Distance	Time per transfer (nsec)
0,0	0,1	1	11.12
0,0	0,2	2	11.14
0,0	1,2	3	11.19
0,0	0,4	4	11.38
0,0	3,3	5	11.62
0,0	4,4	6	11.86
0,0	7,7	14	12.57

- 80 bytes are transferred from one eCore to another
- $\bullet \approx 7$ cycles per transfer



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Shared Memory Access

Experiment: To evaluate the performance of the external shared memory, multiple nodes write to the shared memory simultaneously. Each eCore continuously writes blocks of 2 KBytes over 2 seconds and the utilization is measured

	Node (Total No)	Iterations	Utilization
	0,0	61037	0.41
2 * 2 nodes	0,1	48829	0.33
2 2 1100es	1,0	24414	0.17
	1,1	12207	0.08
	0,7 1,7 2,7 3,7	27460+	0.187 each
	(8)	3050+	0.021 each
	(4)	2040+	0.014 each
8 * 8 nodes	(8)	100 - 1000	
	(9)	10 - 100	
	(7)	1 - 10	
	(24)	0	

- Nodes closer to column 7 and row 0 get the best write access
- Write throughput of 150 MB/sec



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Heat Stencil Equation

Five-point star-shaped stencil

$$T_{new_{i,j}} = w_1 * T_{prev_{i,j+1}} + w_2 * T_{prev_{i,j}}$$

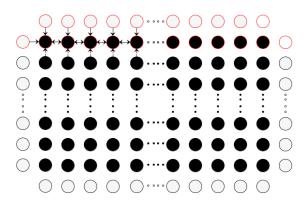
 $+ w_3 * T_{prev_{i,j-1}} + w_4 * T_{prev_{i+1,j}}$
 $+ w_5 * T_{prev_{i-1,i}}$

Implementation

- Hand-tuned unrolled assembly code
- "In-place" implementation
- Size of grid limited by local memory (and size of assembly code)
- All 64 registers used and managed carefully
- Grid initialized in the host and transferred to each eCore
- Computation followed by communication phase in each iteration



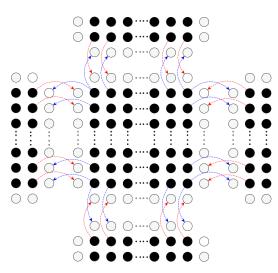
Computation Phase



- Grid sizes of 20 × X. Width of 20 decided based on register availability
- Buffer 2 rows of grid points into registers and perform FMADDs
- Continuous runs of Fused Multiply-Add (FMADD) interleaved with 64-bit load/store
- 5 grid points accumulated at a time
- Each grid point loaded into register only once



Communication Phase



- Synchronization between neighbouring eCores
- Transfers started after neighbour's computation phase
- DMA for boundary transfers

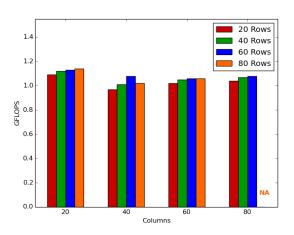


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Floating point performance

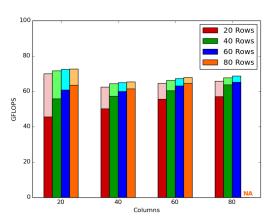
Single-core Floating point performance in GFLOPS



- Stencil evaluated for 50 iterations.
- 81-95% of peak performance

Floating point performance

64-core Floating point performance in GFLOPS



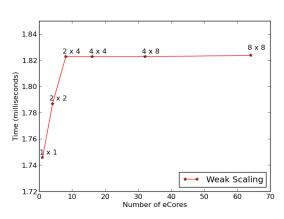
 83% of peak performance with communication





Weak Scaling

Weak Scaling - Number of eCores vs Time

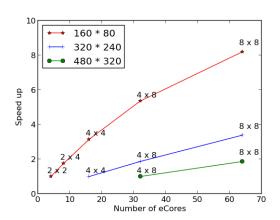


- Number of eCores from 1 to 64
- Vary problem size from 60 × 60 to 480 × 480



Strong Scaling

Strong Scaling - Number of eCores vs Speedup



- Number of eCores from 1 to 64
- Problem size fixed

Conclusions and Future Work

- Heat Stencil running at 65 GFLOPS (83%)
 - ullet pprox 32 GFLOPS/Watt assuming 2W power consumption
 - Double-buffering of boundary regions to overlap computation and communication
- Epiphany platform holds high potential for HPC
 - Considerable effort to extract high performance
- Memory constraint important factor while designing algorithms
 - Streaming algorithm to process higher grid sizes
 - Future version of Epiphany to have 4096 cores (70 GFLOPS/Watt)



Introduction

Questions?